

U.S. Department of Commerce, Patent and Trademark Office				Atty. Docket No.		Serial No.	
				M-15302-1P US		10/798,540	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)				Applicant(s)			
				Savastiouk et al.			
				Filing Date		Group	
				March 10, 2004		Unassigned	

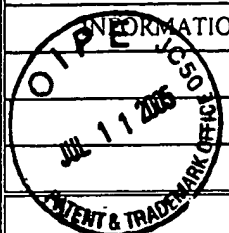
U.S. Patent Documents							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
KL	AA	6,175,158	16 Jan. 2001	Degani et al.			
KL	AB	6,661,088	9 Dec. 2003	Yoda et al.			
KL	AC	2002/0036340	28 Mar. 2002	Matsuo et al.			
KL	AD	2003/0047798	13 Mar. 2003	Halahan			
KL	AE	2002/0074637	20 Jun. 2002	McFarland			
KL	AF	2002/0175421	28 Nov. 2002	Kimura			
KL	AG	2003/0080437	1 May 2003	Gonzalez et al.			
KL	AH	2002/0048916	25 Apr. 2002	Yanagida			
KL	AI						

Foreign Patent Documents							Translation	
	Document	Date	Country	Class	Subclass		Yes	No

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)		

Examiner <u>Kyoung Lee</u>	Date Considered <u>10/27/05</u>
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KL	AA	2003/0199123	23 Oct. 2003	Siniaguine				
KL	AB	2001/0019178	6 Sep. 2001	Brofman et al.				
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	AD							
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KL	AA	5,391,514	Feb. 1995	Gall et al.			
KL	AB	6,903,443	Jun. 2005	Farnworth et al.			
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KL	AC	2003/0080437	1 May 2003	Gonzalez et al.			
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KL	AE	2002/0036340	28 Mar. 2002	Matsuo et al.			
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KL	AI	2003/0116859	26 Jun. 2003	Hashimoto			
KL	AJ	6,322,903	27 Nov. 2001	Siniaguine et al.			

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KL	AA	2003/0047798A1	13 Mar 2003	Halahan			
KL	AB	2003/0226254A1	11 Dec. 2003	Koning et al.			
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KL	AG	6,163,456	19 Dec. 2000	Suzuki et al.			
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KL	AH	WO 01/45476 A1	21 Jun. 2001	PCT			
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KL	AI	Perfecto, Eric; Lee, Kang-Wook; Hamel, Harvey; Wassick, Thomas; Cline, Christopher; Oonk, Matthew; Feger, Claudius; McHerron, Dale, "Evaluation of Cu Capping Alternatives for Polyimide-Cu MCM-D" IEEE, 2001 Electronic Components and Technology Conference.					
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KL	AL	Ekstrom; Bjorn "Thin Film Silicon Substrates For Lead Frame Packages" Advancing Microelectronics - May/June 2003, pages 6-7.					
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KL	AO	"Staychip; 2078E No-Flow Fluxing Underfill; For Soldering Sn/Pb eutectic solder bumps to common pad metallizations Preliminary Technical Bulletin" Semiconductor Products, Technical Bulletin; Cookson Electronics.					
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KL	AQ	Sperling, Ed; Electronic News, 9/17/2003.	
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KL	AV	Guenin, Bruce M. "The Many Flavors of Ball Grid Array Packages" Electronics Cooling, Feb. 2002, pages 1-7.	
KL	AW	"HPMX-5001: Demonstration Circuit Board: Application Brief 102" Hewlett Packard, pages 1-10.	
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KL	AZ	Wang, Tie; Tung, Francisca; Foo, Louis; and Dutta, Vivek "Studies on A Novel Flip-Chip Interconnect Structure - Pillar Bump" Advanpack Solutions Pte Ltd, 2001 IEEE, 2001 Electronic Components and Technology Conference.	
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KL	BC	Zama, Satoru; Baldwin, Daniel F; Hikami, Toshiya; Murata, Hideaki "Flip Chip Interconnect Systems Using Wire Stud Bumps and Lead Free Solder," 2000 IEEE Electronic Components and Technology Conference, pages 1111-1117.	
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